

Reactive sputtering for highly oriented HfN film growth on Si(100) substrate

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KEYWORDS: HfN, HfSi₂, epitaxial growth, reactive magnetron sputtering.

Hafnium nitride have excellent properties such as high melting point, high hardness, low resistivity, which makes them potential in many technological fields. HfN have been investigated for diffusion barriers in semiconductor devices. HfSi₂ has been used for high temperature oxidation resistant coatings. However, there are no detailed studies for growth of epitaxial HfN/HfSi₂ films on Si substrate.

HfN films were grown on Si(100) substrates by reactive DC magnetron sputtering with Ar/N₂ gas mixture using a Hf target. The deposition was carried out by varying N₂ flow ratio and the power at 5 mTorr and 850°C.

XRD results with cross-sectional TEM/STEM show that low N₂ flow ratio favors the formation of the HfSi₂ interlayer between HfN and Si, while no HfSi₂ diffraction peaks can be seen for high N₂ flow ratio of 12.5% (Fig. 1). Also, increasing the applied power for sputtering results in the increase of the HfN peak intensity ratio of (200)/(111). Furthermore, it is shown that the orthorhombic HfSi₂ interlayer is in epitaxy with Si (100) and those (100) oriented HfN grains are found in epitaxy with both HfSi₂ and Si as well. The epitaxial relationship is HfN (100) [011] // HfSi₂ (020) [100] // Si (100) [011].

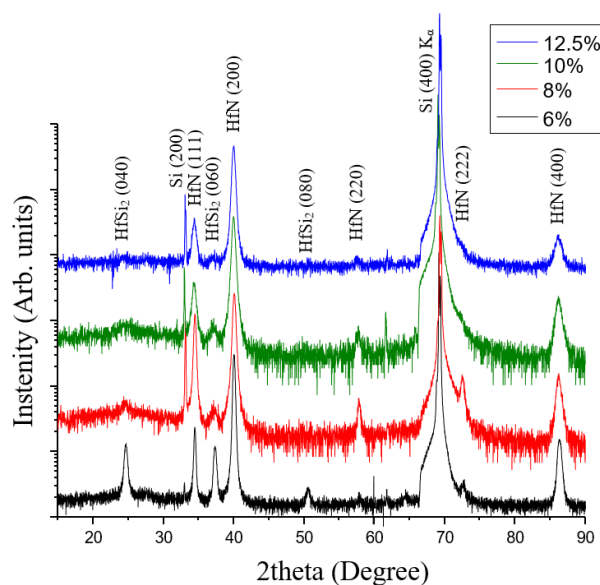


Fig. 1 XRD of HfN films grown on Si with different N₂ ratio.

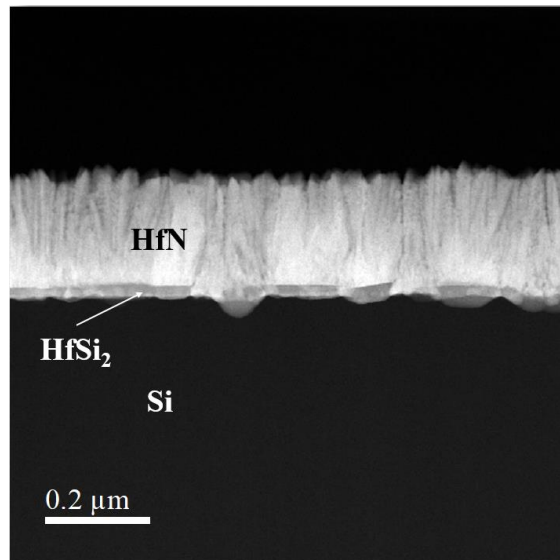


Fig. 2 STEM-ADF image of HfN/Si in cross-section view. HfSi₂ is present between HfN and Si interface.

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